

- **21:3 Data Channel Compression at up to 196 Million Bytes per Second Throughput**
- **Suited for SVGA, XGA, or SXGA Data Transmission From Controller to Display With Very Low EMI**
- **21 Data Channels Plus Clock In Low-Voltage TTL Inputs and 3 Data Channels Plus Clock Out Low-Voltage Differential Signaling (LVDS) Outputs**
- **Operates From a Single 3.3-V Supply and 89 mW (Typ)**
- **Ultralow-Power 3.3-V CMOS Version of the SN75LVDS84. Power Consumption About One Third of the 'LVDS84**
- **Packaged in Thin Shrink Small-Outline Package (TSSOP) With 20 Mil Terminal Pitch**
- **Consumes Less Than 0.54 mW When Disabled**
- **Wide Phase-Lock Input Frequency Range: 31 MHz to 75 MHz**
- **No External Components Required for PLL**
- **Outputs Meet or Exceed the Requirements of ANSI EIA/TIA-644 Standard**
- **SSC Tracking Capability of 3% Center Spread at 50-kHz Modulation Frequency**
- **Improved Replacement for SN75LVDS84 and NSC's DS90CF363A 3-V Device**
- **Available in Q-Temp Automotive High Reliability Automotive Applications Configuration Control / Print Support Qualification to Automotive Standards**

DGG PACKAGE (TOP VIEW)

D4	1	48	D3
V _{CC}	2	47	D2
D5	3	46	GND
D6	4	45	D1
GND	5	44	D0
D7	6	43	NC
D8	7	42	LVDSGND
V _{CC}	8	41	Y0M
D9	9	40	Y0P
D10	10	39	Y1M
GND	11	38	Y1P
D11	12	37	LVDSV _{CC}
D12	13	36	LVDSGND
NC	14	35	Y2M
D13	15	34	Y2P
D14	16	33	CLKOUTM
GND	17	32	CLKOUTP
D15	18	31	LVDSGND
D16	19	30	PLL _{GND}
D17	20	29	PLL _{V_{CC}}
V _{CC}	21	28	PLL _{GND}
D18	22	27	SHTDN
D19	23	26	CLKIN
GND	24	25	D20

NC – Not Connected

description

The SN75LVDS84A and SN65LVDS84AQ FlatLink transmitters contains three 7-bit parallel-load serial-out shift registers, and four low-voltage differential signaling (LVDS) line drivers in a single integrated circuit. These functions allow 21 bits of single-ended LVTTTL data to be synchronously transmitted over 3 balanced-pair conductors for receipt by a compatible receiver, such as the SN75LVDS82 or SN75LVDS86/86A.

When transmitting, data bits D0 – D20 are each loaded into registers of the 'LVDS84A upon the falling edge. The internal PLL is frequency-locked to CLKIN and then used to unload the data registers in 7-bit slices. The three serial streams and a phase-locked clock (CLKOUT) are then output to LVDS output drivers. The frequency of CLKOUT is the same as the input clock, CLKIN.



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SN75LVDS84A, SN65LVDS84AQ FLATLINK™ TRANSMITTER

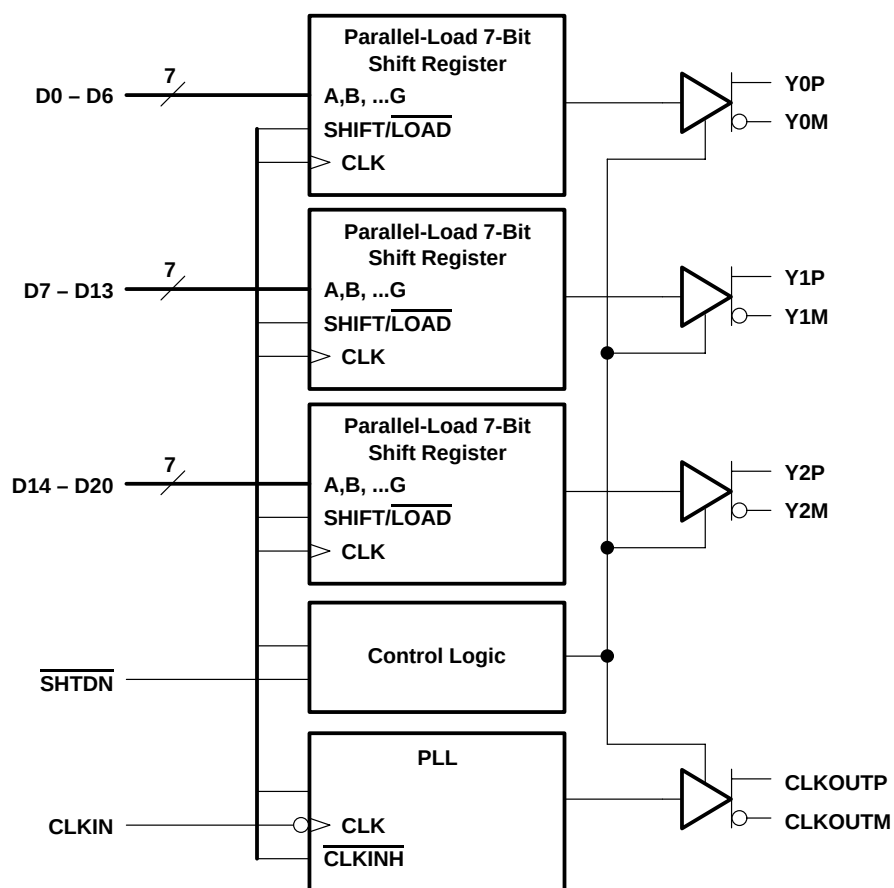
SLLS354E – MAY 1999 – REVISED JANUARY 2001

description (continued)

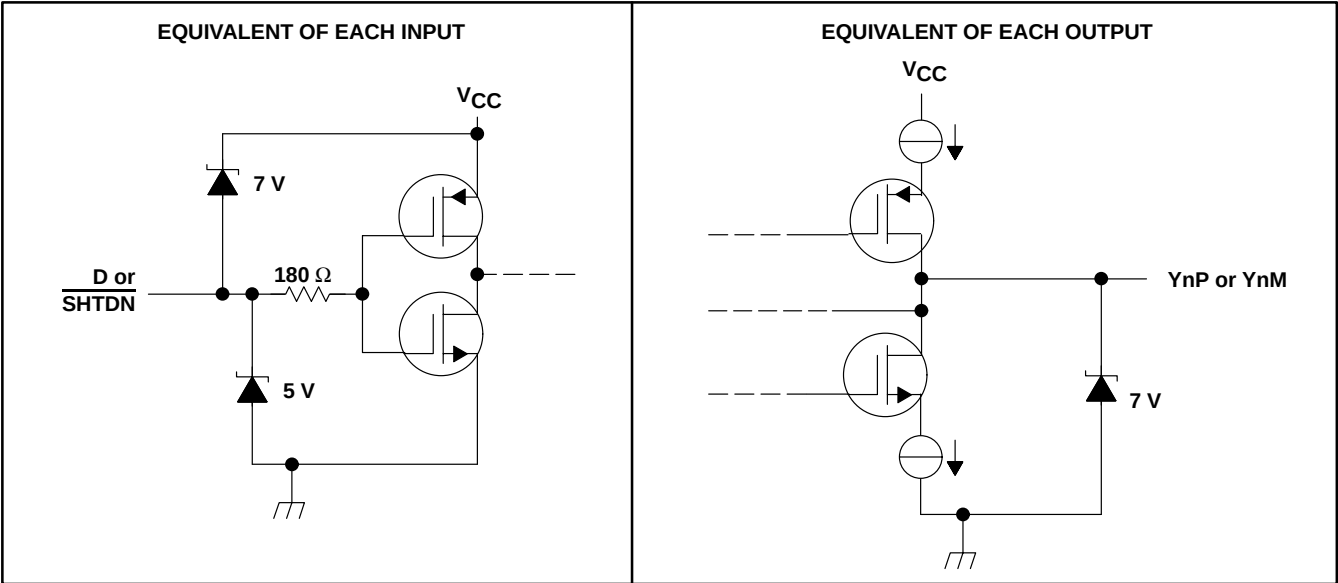
The 'LVDS84A requires no external components and little or no control. The data bus appears the same at the input to the transmitter and output of the receiver with the data transmission transparent to the user(s). The only user intervention is the possible use of the shutdown/clear ($\overline{\text{SHTDN}}$) active-low input to inhibit the clock and shut off the LVDS output drivers for lower power consumption. A low-level on this signal clears all internal registers to a low level.

The SN75LVDS84A is characterized for operation over ambient free-air temperatures of 0°C to 70°C. The SN65LVDS84AQ is characterized for operation over the full Automotive temperature range of -40°C to 125°C.

functional block diagram



schematics of input and output



absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage range, V_{CC} (see Note 1)	–0.5 V to 4 V
Input and output voltage ranges, V_I , V_O (all terminals)	–0.5 V to $V_{CC} + 0.5$ V
Continuous total power dissipation	See Dissipation Rating Table
Operating virtual junction temperature range, T_J	–40°C to 150°C
Electrostatic discharge: ESD machine model	200 V
ESD human-body model	6000 V
ESD charged-device model	1500 V
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to the GND terminals.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR [‡] ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
DGG	1637 mW	13.1 mW/°C	1048 mW	327 mW

[‡] This is the inverse of the junction-to-ambient thermal resistance when board mounted and with no air flow.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		3	3.3	3.6	V
High-level input voltage, V _{IH}		2			V
Low-level input voltage, V _{IL}				0.8	V
Differential load impedance, Z _L		90		132	Ω
Operating free-air temperature, T _A	SN75LVDS84A	0		70	°C
	SN65LVDS84AQ	−40		125	

SN75LVDS84A, SN65LVDS84AQ FLATLINK™ TRANSMITTER

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timing requirements

	MIN	NOM	MAX	UNIT
t_C Input clock period	13.3	t_C	32.4	ns
t_W Pulse duration, high-level input clock	$0.4t_C$		$0.6t_C$	ns
t_t Transition time, input signal			5	ns
t_{SU} Setup time, data, D0 – D20 valid before CLKIN↓ (see Figure 2)	3			ns
t_h Hold time, data, D0 – D20 valid after CLKIN↓ (see Figure 2)	1.5			ns

electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{IT} Input threshold voltage			1.4		V
$ V_{OD} $ Differential steady-state output voltage magnitude	$R_L = 100\ \Omega$, See Figure 3	247		454	mV
$\Delta V_{OD} $ Change in the steady-state differential output voltage magnitude between opposite binary states				50	mV
$V_{OC(SS)}$ Steady-state common-mode output voltage	$R_L = 100\ \Omega$, See Figure 3	1.125		1.375	V
$V_{OC(PP)}$ Peak-to-peak common-mode output voltage			80	150	mV
I_{IH} High-level input current	$V_{IH} = V_{CC}$				μA
	SN75LVDS84A			20	
	SN65LVDS84AQ			25	
I_{IL} Low-level input current	$V_{IL} = 0$			± 10	μA
I_{OS} Short-circuit output current	$V_O(Y_n) = 0$		–6	± 24	mA
	$V_{OD} = 0$		–6	± 12	mA
I_{OZ} High-impedance output current	$V_O = 0$ to V_{CC}			± 10	μA
$I_{CC(AVG)}$ Quiescent supply current (average)	Disabled, All inputs at GND	SN75LVDS84A	15	150	μA
		SN65LVDS84AQ	15	170	
	Enabled, $R_L = 100\ \Omega$ (4 places) Gray-scale pattern (see Figure 4)	$f = 65\ \text{MHz}$	27	35	mA
		$f = 75\ \text{MHz}$	30	38	
	Enabled, $R_L = 100\ \Omega$, (4 places) Worst-case pattern (see Figure 5)	$f = 65\ \text{MHz}$	28	36	
		$f = 75\ \text{MHz}$	31	39	
C_I Input capacitance			2		pF

† All typical values are at $V_{CC} = 3.3\ \text{V}$, $T_A = 25^\circ\text{C}$.



switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
t _{d0} Delay time, CLKOUT↑ to serial bit position 0	t _c = 15.38 ns (± 0.2%), Input clock jitter < 50 ps [‡] , See Figure 6	–0.2		0.2	ns
t _{d1} Delay time, CLKOUT↑ to serial bit position 1		$\frac{1}{7}t_c - 0.2$		$\frac{1}{7}t_c + 0.2$	
t _{d2} Delay time, CLKOUT↑ to serial bit position 2		$\frac{2}{7}t_c - 0.2$		$\frac{2}{7}t_c + 0.2$	
t _{d3} Delay time, CLKOUT↑ to serial bit position 3		$\frac{3}{7}t_c - 0.2$		$\frac{3}{7}t_c + 0.2$	
t _{d4} Delay time, CLKOUT↑ to serial bit position 4		$\frac{4}{7}t_c - 0.2$		$\frac{4}{7}t_c + 0.2$	
t _{d5} Delay time, CLKOUT↑ to serial bit position 5		$\frac{5}{7}t_c - 0.2$		$\frac{5}{7}t_c + 0.2$	
t _{d6} Delay time, CLKOUT↑ to serial bit position 6		$\frac{6}{7}t_c - 0.2$		$\frac{6}{7}t_c + 0.2$	
t _{sk(o)} Output skew, t _n – $\frac{n}{7}t_c$		–0.2		0.2	ns
t _{d7} Delay time, CLKIN↓ to CLKOUT↑	t _c = 15.38 ns (± 0.2%), Input clock jitter < 50 ps [‡] , See Figure 6		2.7		ns
	t _c = 13.33 ns ~ 32.25 ns (± 0.2%), Input clock jitter < 50 ps [‡] , See Figure 6	1		4.5	
Δt _{c(o)} Cycle time, output clock jitter [§]	t _c = 15.38 + 0.308 sin (2π500E3t) ± 0.05 ns, See Figure 7		±62		ps
	t _c = 15.38 + 0.308 sin (2π3E6t) ± 0.05 ns, See Figure 7		±121		
t _w Pulse duration, high-level output clock			$\frac{4}{7}t_c$		ns
t _t Transition time, differential output voltage (t _r or t _f)	See Figure 3		700	1500	ps
t _{en} Enable time, SHTDN↑ to phase lock (Y _n valid)	See Figure 8		1		ms
t _{dis} Disable time, SHTDN↓ to off state (CLKOUT low)	See Figure 9		6.5		ns

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

[‡] |Input clock jitter| is the magnitude of the change in the input clock period.

[§] Output clock jitter is the change in the output clock period from one cycle to the next cycle observed over 15000 cycles.

SN75LVDS84A, SN65LVDS84AQ FLATLINK™ TRANSMITTER

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PARAMETER MEASUREMENT INFORMATION

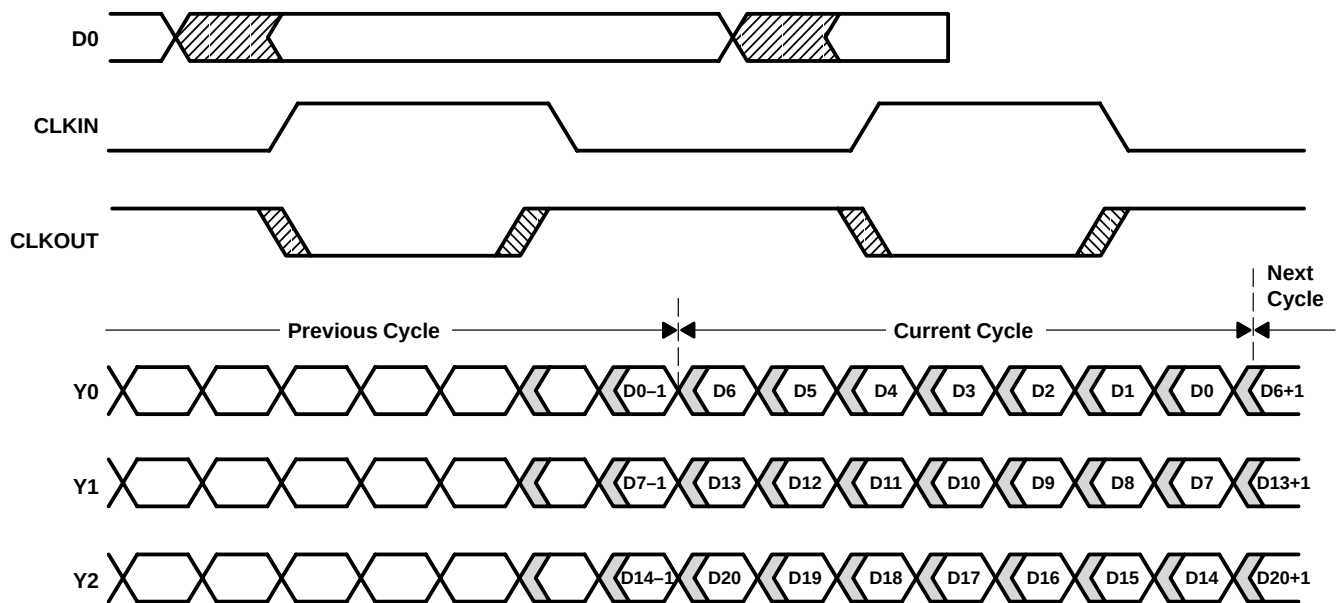
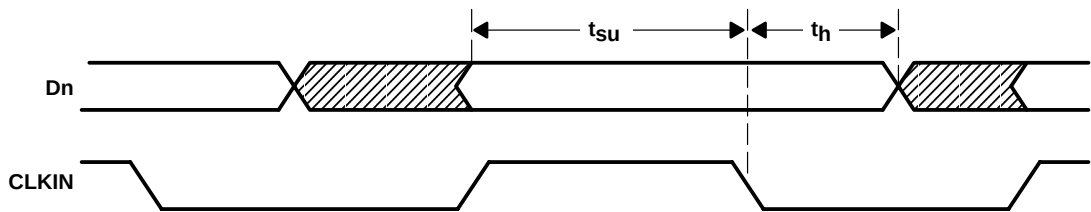
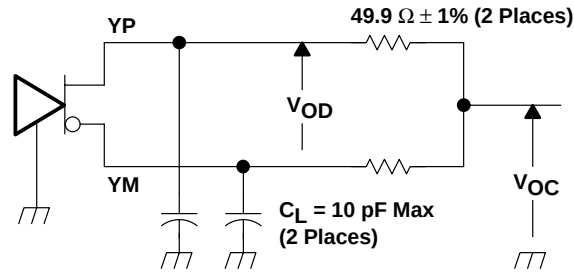


Figure 1. Typical Load and Shift Sequences



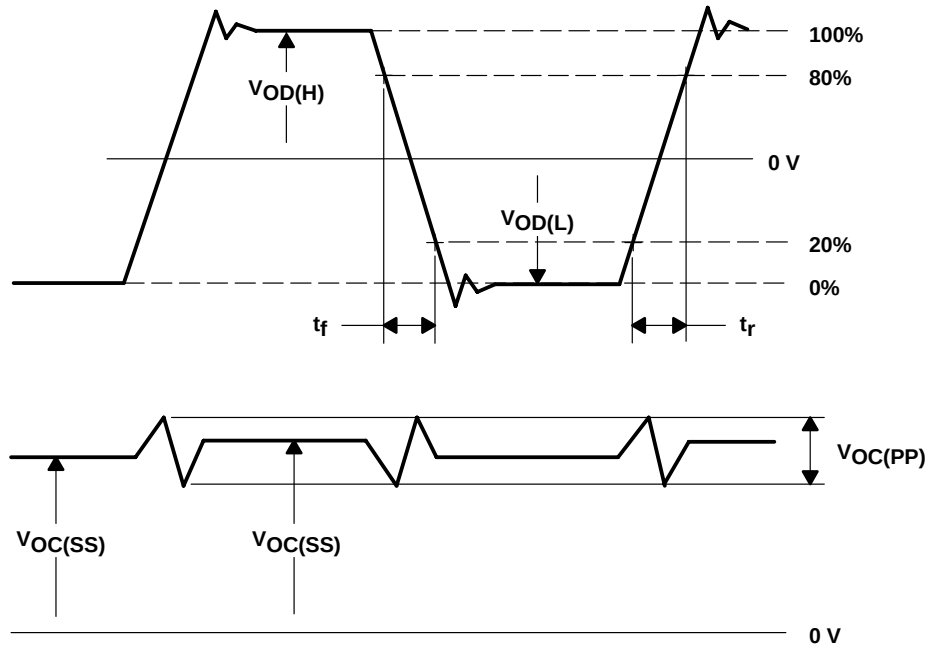
NOTE A: All input timing is defined at 1.4 V on an input signal with a 10%-to-90% rise or fall time of less than 5 ns.

Figure 2. Setup and Hold Time Definition



NOTE A: The lumped instrumentation capacitance for any single-ended voltage measurement is less than or equal to 10 pF. When making measurements at YP or YM, the complementary output is similarly loaded.

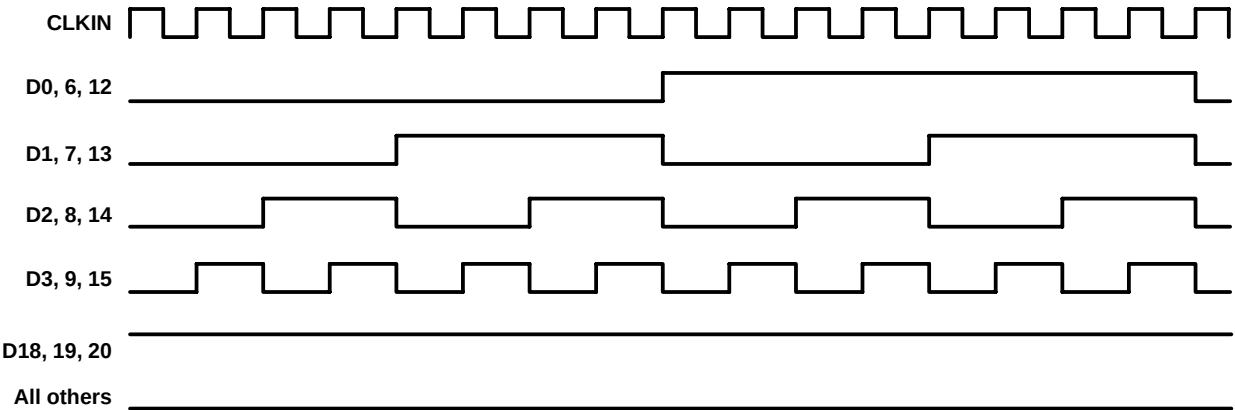
(a) SCHEMATIC



(b) WAVEFORMS

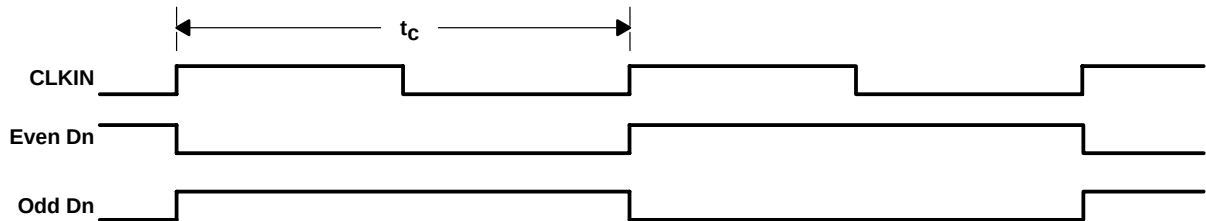
Figure 3. Test Load and Voltage Definitions for LVDS Outputs

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The 16-grayscale test-pattern test device power consumption for a typical display pattern.
B. $V_{IH} = 2\text{ V}$ and $V_{IL} = 0.8\text{ V}$

Figure 4. 16-Grayscale Test-Pattern Waveforms



NOTES: A. The worst-case test pattern produces nearly the maximum switching frequency for all of the LVDS outputs.
B. $V_{IH} = 2\text{ V}$ and $V_{IL} = 0.8\text{ V}$

Figure 5. Worst-Case Test-Pattern Waveforms

PARAMETER MEASUREMENT INFORMATION

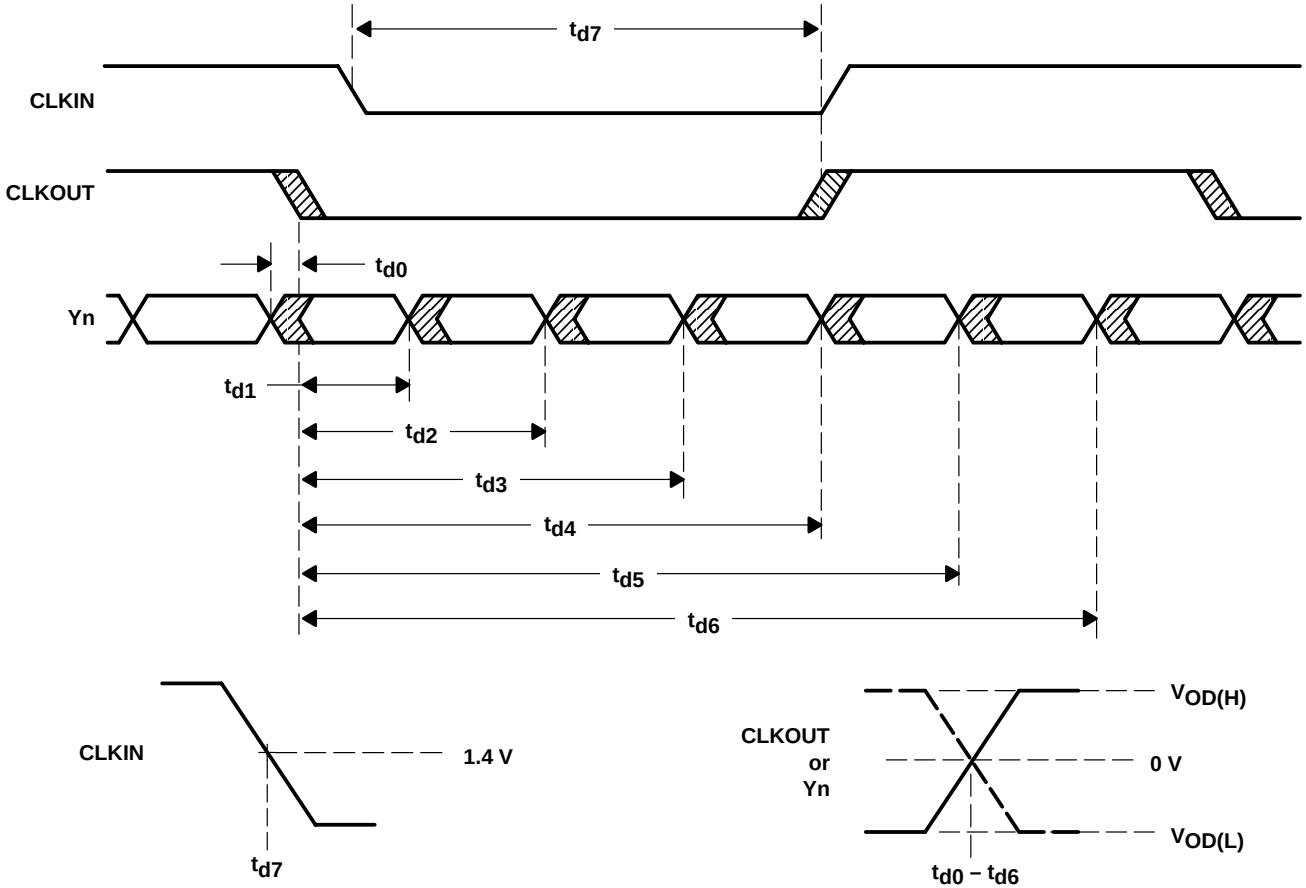


Figure 6. Timing Definitions

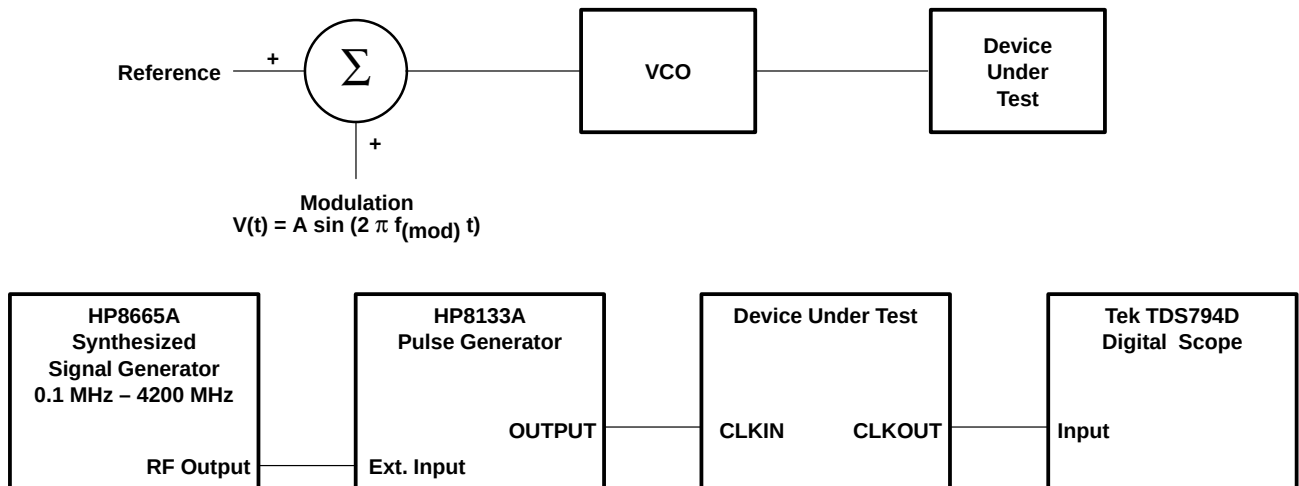


Figure 7. Clock Jitter Test Setup

TYPICAL CHARACTERISTICS

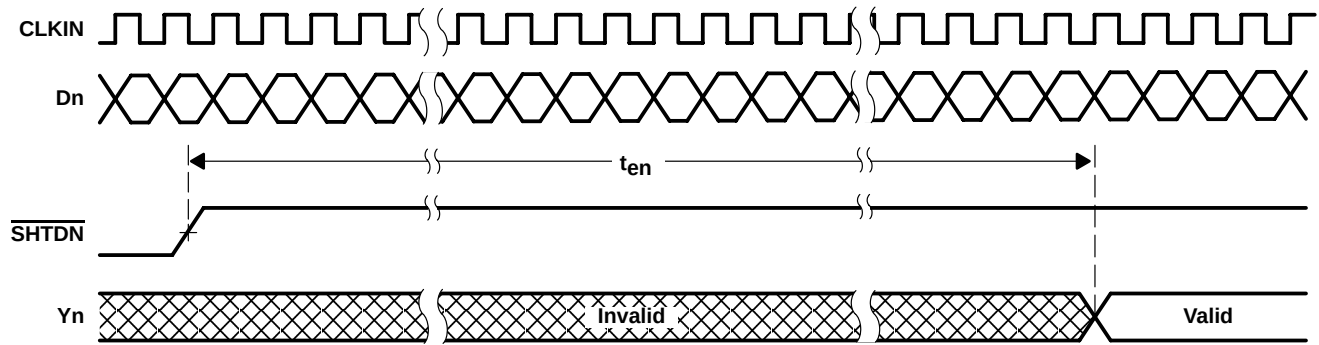


Figure 8. Enable Time Waveforms

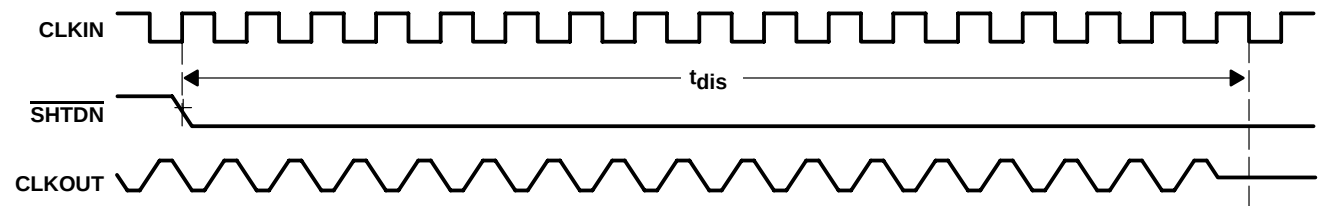


Figure 9. Disable Time Waveforms

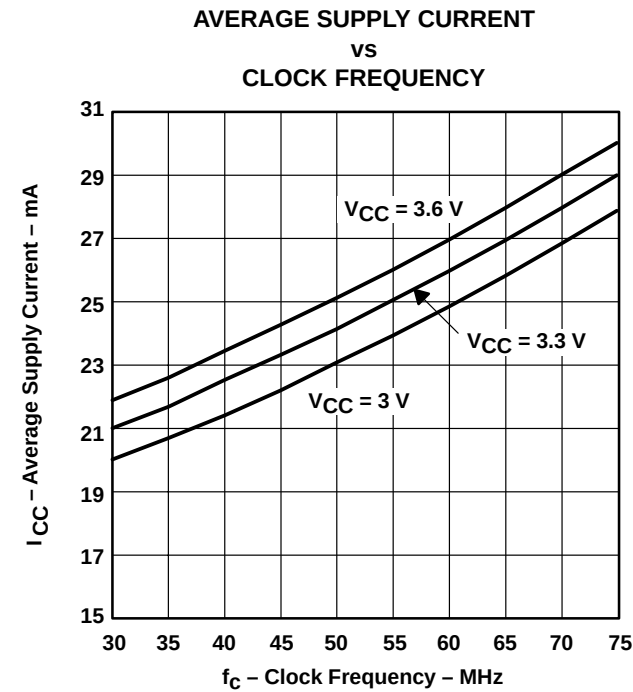


Figure 10. Grayscale Input Pattern

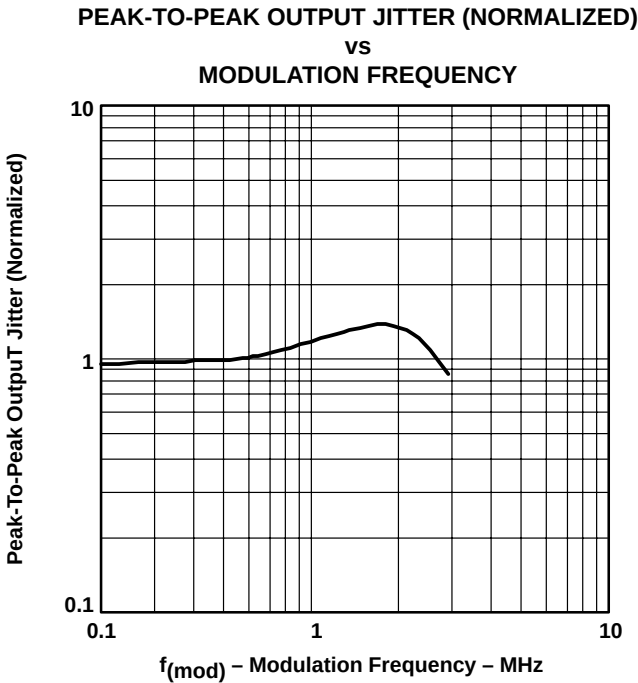
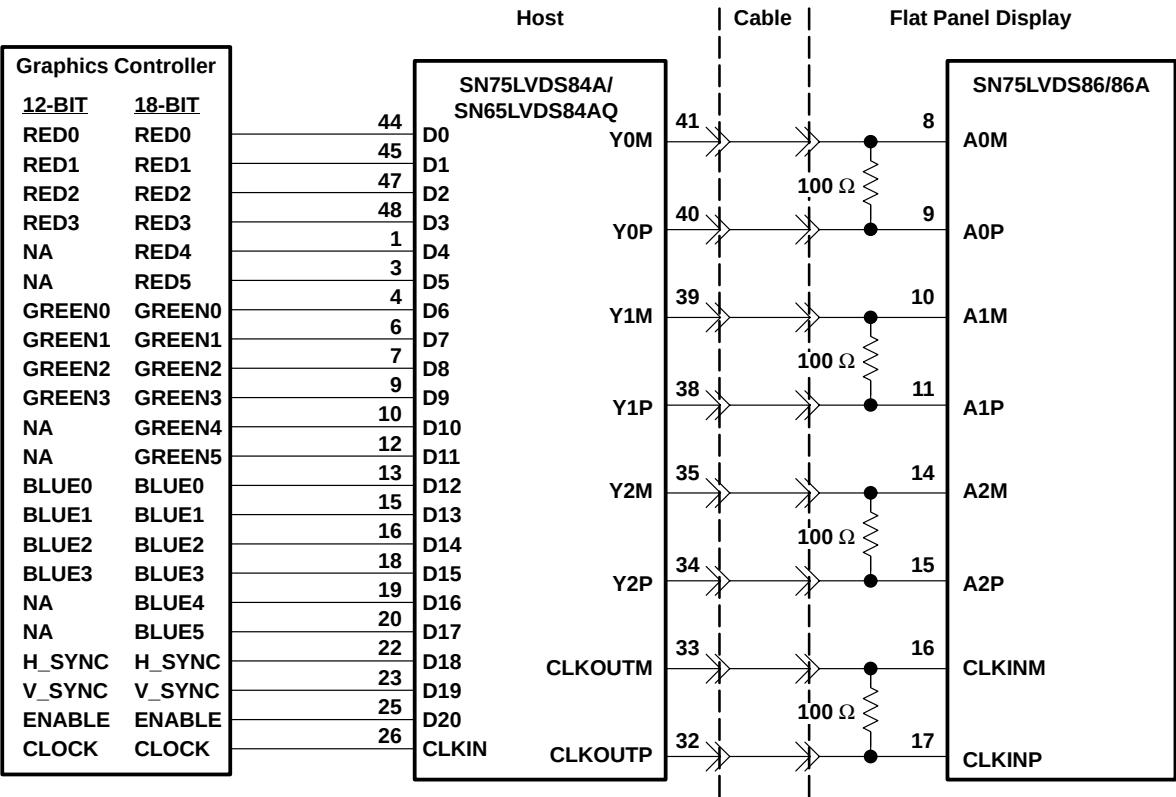


Figure 11. Output Period Jitter vs Modulation Frequency

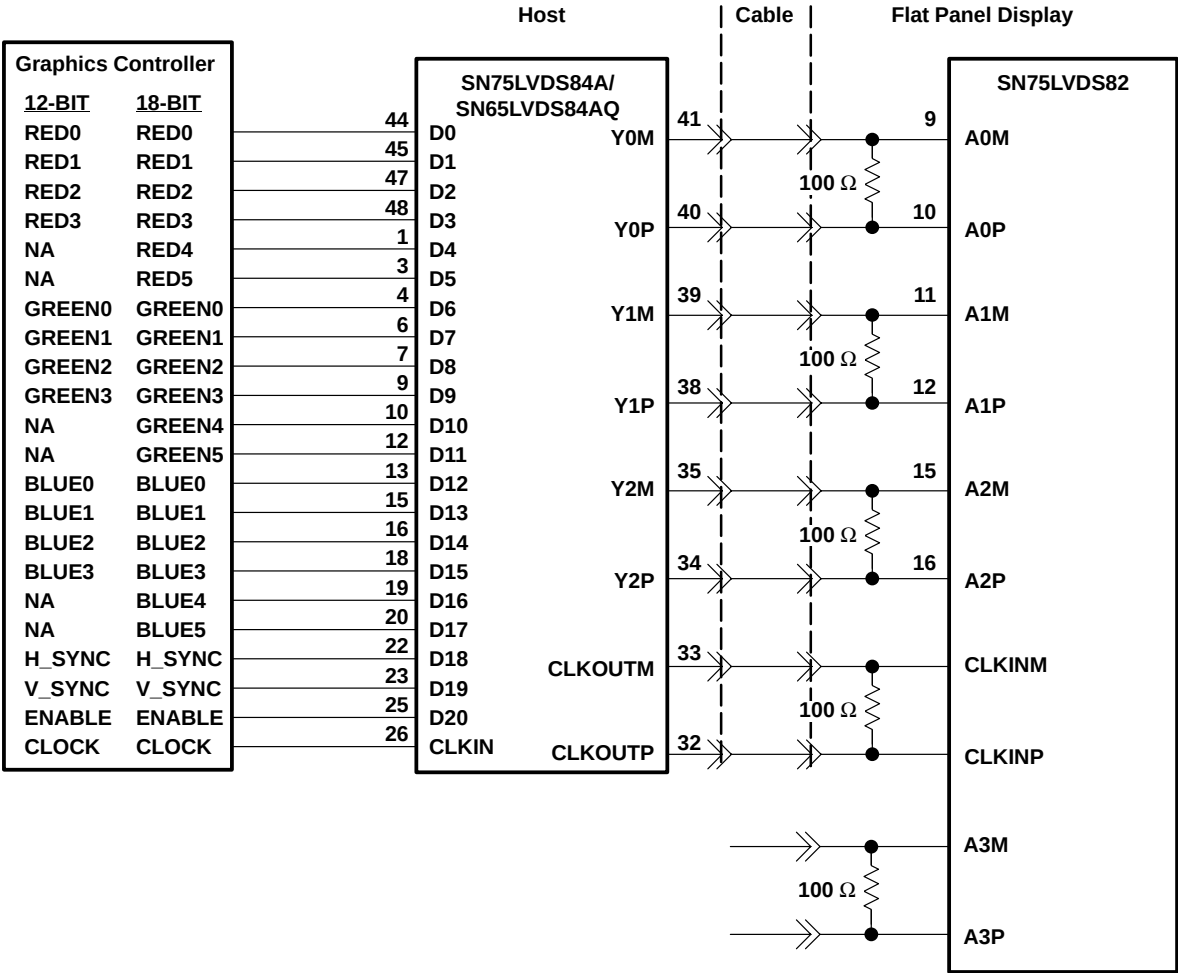
APPLICATION INFORMATION



- NOTES: A. The five 100- Ω terminating resistors are recommended to be 0603 types.
B. NA – not applicable, these unused inputs should be left open.

Figure 12. Color Host to LCD Panel Application

APPLICATION INFORMATION



NOTES: A. The four 100-Ω terminating resistors are recommended to be 0603 types.
B. NA – not applicable, these unused inputs should be left open.

Figure 13. 18-Bit Color Host to 24-Bit LCD Display Panel Application

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65LVDS84AQDGG	ACTIVE	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN65LVDS84AQDGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN75LVDS84ADGG	ACTIVE	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN75LVDS84ADGGG4	ACTIVE	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN75LVDS84ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN75LVDS84ADGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

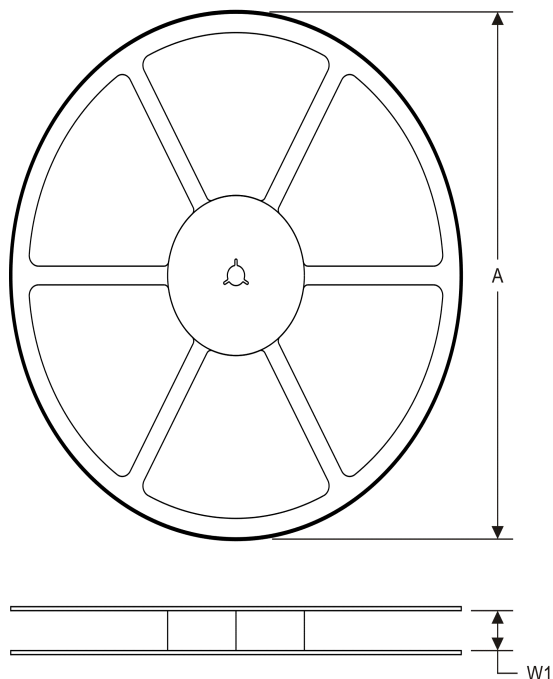
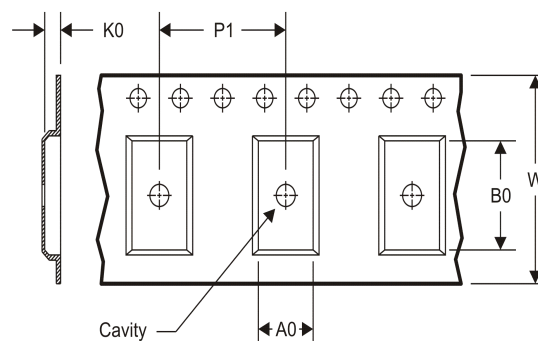
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


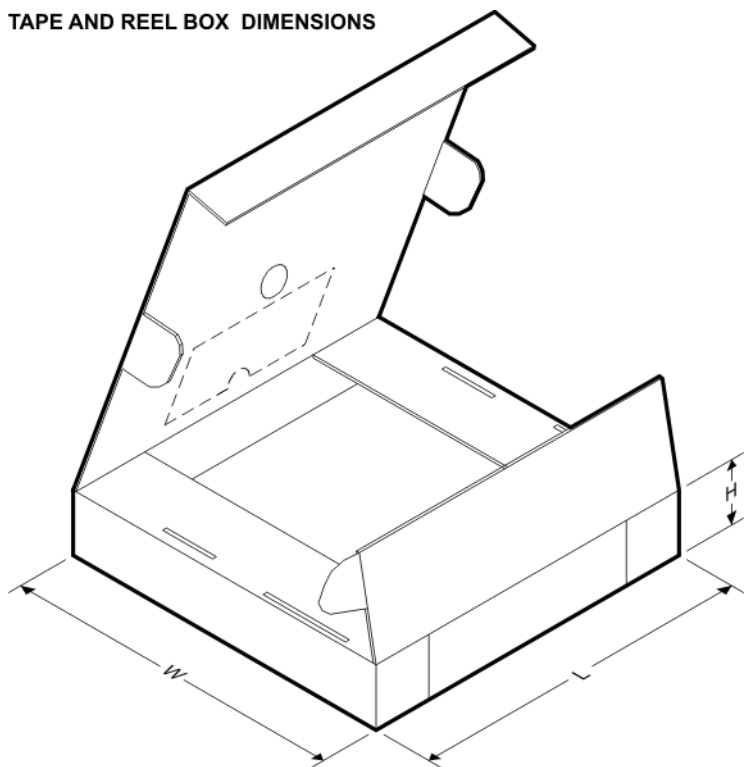
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LVDS84AQDGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN75LVDS84ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



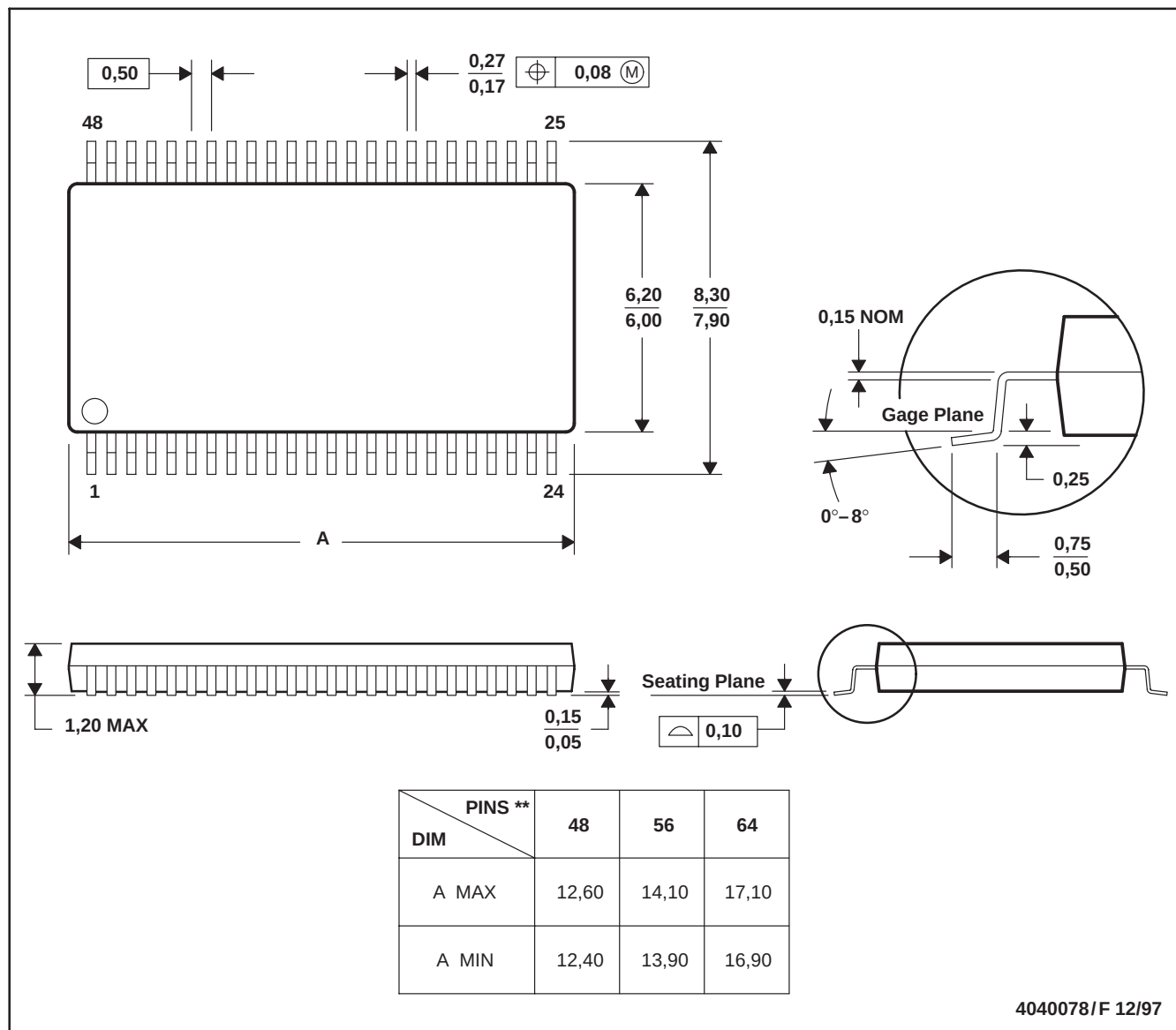
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LVDS84AQDGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN75LVDS84ADGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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